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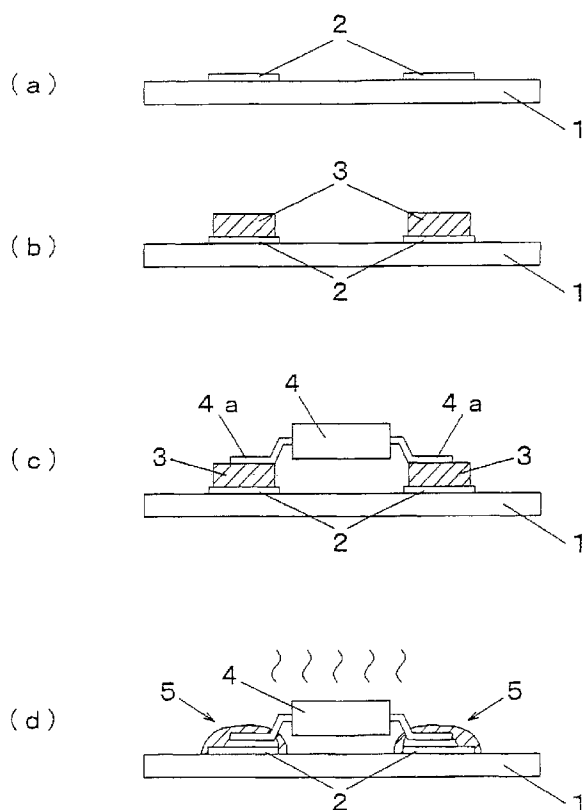
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(54) Title: SOLDER COMPOSITION, CONNECTING PROCESS WITH SOLDERING, AND CONNECTION STRUCTURE WITH SOLDERING



(57) Abstract: There is provided a solder composition which contains: (1) a metal material comprising solder particles, and (2) a thermosetting flux material comprising a thermosetting resin and a solid resin which changes to be in its liquid-like state when heated with a proviso that the thermosetting resin is excluded from the solid resin, wherein a temperature at which the solid resin changes to be in the liquid-like state is lower than a temperature at which the thermosetting resin starts to cure.



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